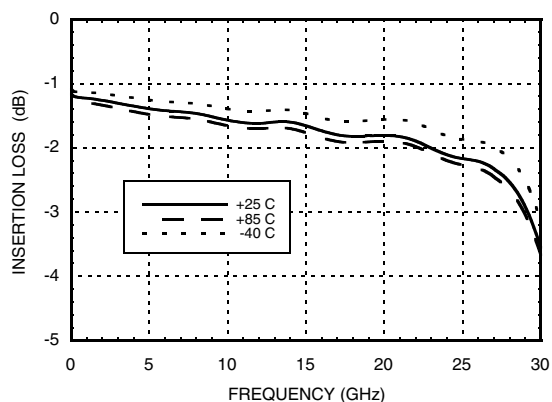
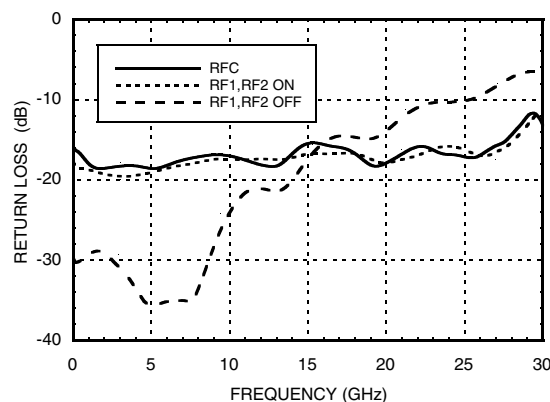
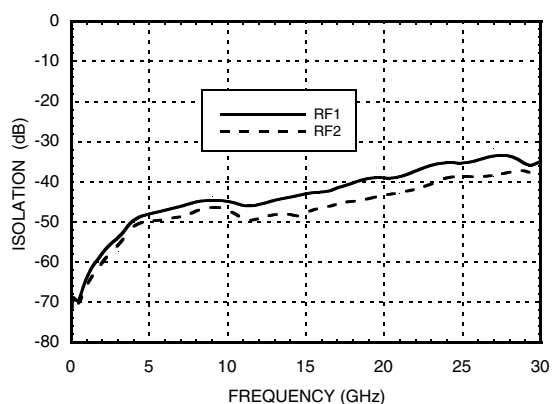
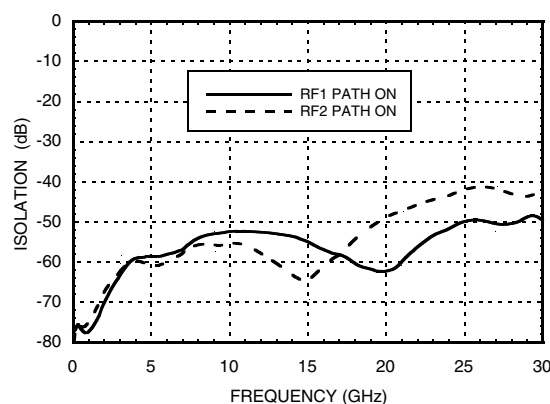
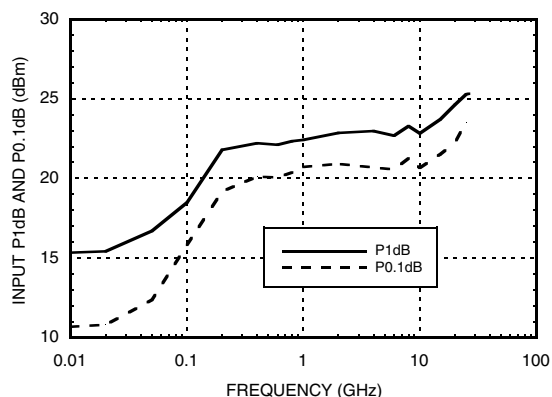
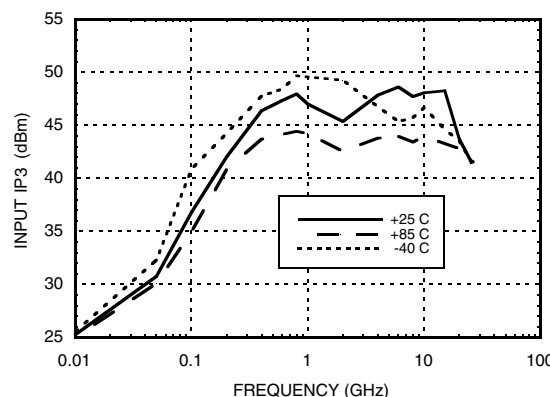


**GaAs MMIC SPDT NON-REFLECTIVE
SWITCH, DC - 28.0 GHz**
Insertion Loss

Return Loss

Isolation Between Ports RFC and RF1/RF2

Isolation Between Ports RF1 and RF2

**Input P1dB and P0.1dB
Compression Point**

Input Third Order Intercept Point




GaAs MMIC SPDT NON-REFLECTIVE SWITCH, DC - 28.0 GHz

Absolute Maximum Ratings

RF Input Power (A,B = 0V/-5V)	+25 dBm
Control Voltage Range (A & B)	+5.0V to -7.5V
Hot Switch Power Level (A,B = 0V/-5V)	+22 dBm
Channel Temperature	150 °C
Continuous Pdiss (T=85°C) (derate 3.3 mW/°C above 85°C) (Insertion Loss Path)	0.215 W
Thermal Resistance (Insertion Loss Path)	302 °C/W
Continuous Pdiss (T=85°C) (derate 5.6 mW/°C above 85°C) (Terminated Path)	0.363 W
Thermal Resistance (Terminated Path)	179 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C
ESD Sensitivity (HBM)	Class 1A

Control Voltages

State	Bias Condition
Low	0 to -0.5V @ 10 uA Max.
High	-5V @ 3 uA Typ. to -7V @ 10 uA Typ. (± 0.5V)

Truth Table

Control Input		Signal Path State	
A	B	RFC to RF1	RFC to RF2
High	Low	On	Off
Low	High	Off	On

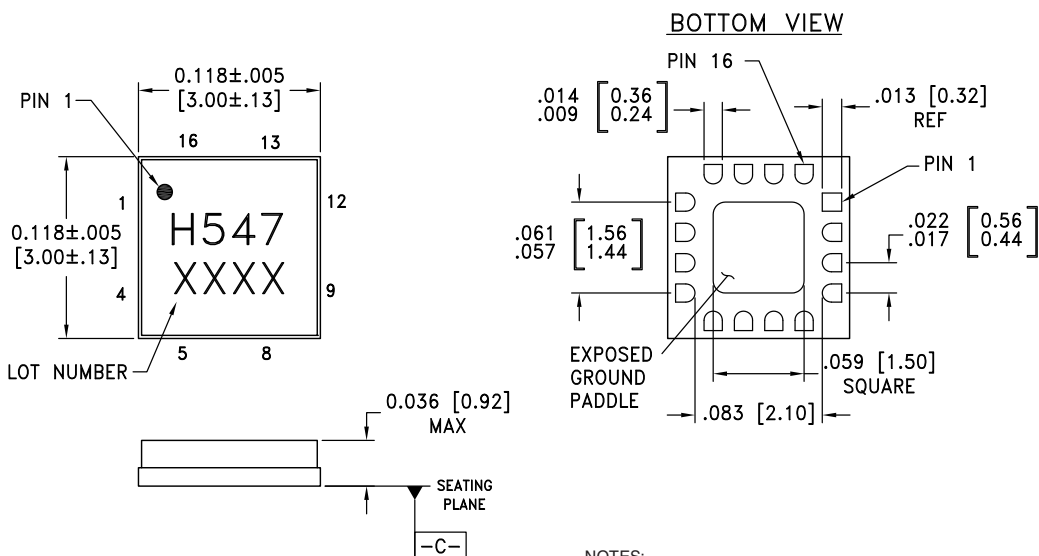


**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**




GaAs MMIC SPDT NON-REFLECTIVE SWITCH, DC - 28.0 GHz

Outline Drawing



NOTES:

1. PACKAGE BODY MATERIAL: ALUMINA.
2. LEAD AND GROUND PADDLE PLATING: GOLD FLASH OVER NICKEL.
3. DIMENSIONS ARE IN INCHES (MILLIMETERS).
4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
5. PACKAGE WARP SHALL NOT EXCEED 0.05MM DATUM .
6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.


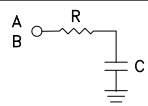
Package Information

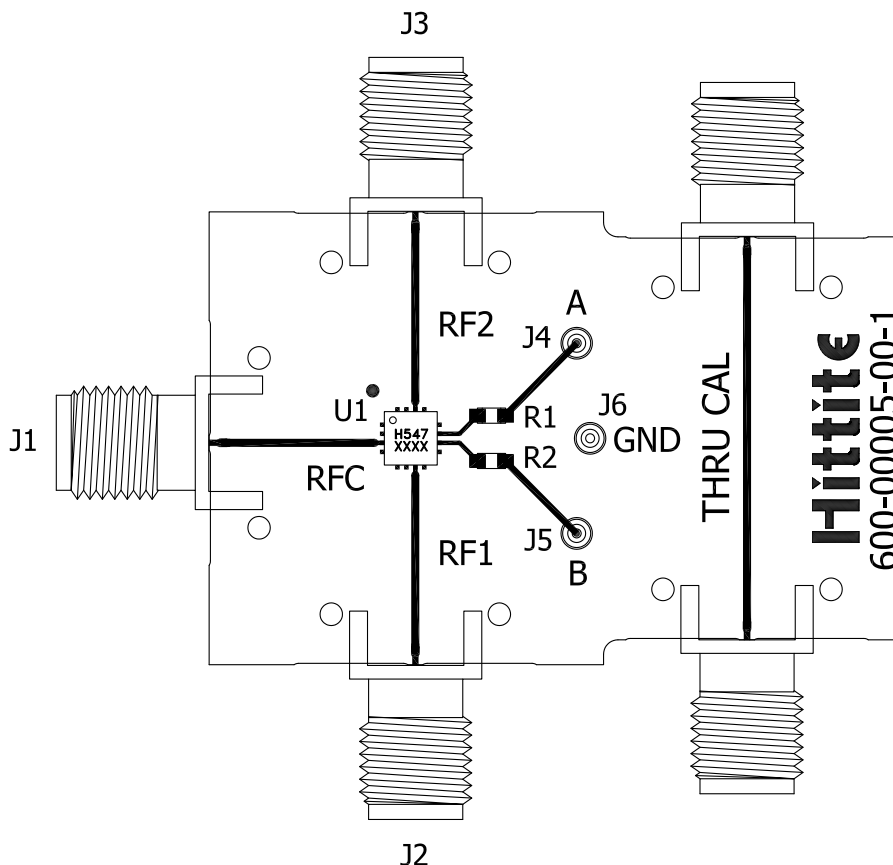
Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[2]
HMC547LC3	Alumina, White	Gold over Nickel	MSL3 ^[1]	H547 XXXX

[1] Max peak reflow temperature of 260 °C

[2] 4-Digit lot number XXXX


**GaAs MMIC SPDT NON-REFLECTIVE
SWITCH, DC - 28.0 GHz**
Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 5, 9, 12, 16	N/C	This pin should be connected to PCB RF ground to maximize isolation	
2, 4, 6, 8, 13, 15	GND	Package bottom has exposed metal paddle that must also be connected to PCB RF ground.	
3, 7, 14	RFC, RF1, RF2	This pin is DC coupled and matched to 50 Ohm. Blocking capacitors are required if RF line potential is not equal to 0V.	
10	B	See truth table and control voltage table.	
11	A	See truth table and control voltage table.	


**GaAs MMIC SPDT NON-REFLECTIVE
SWITCH, DC - 28.0 GHz**
Evaluation PCB

List of Materials for Evaluation PCB EVAL01-HMC547LC3 ^[1]

Item	Description
J1 - J3	PCB Mount SRI SMA Connector
J4 - J6	DC Pin
R1 - R2	100 Ohm Resistor, 0603 Pkg.
U1	HMC547LC3 SPDT Switch
PCB ^[2]	600-00005-00-1 Evaluation PCB

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the application should be generated with proper RF circuit design techniques. Signal lines at the RF port should have 50 Ohm impedance and the package ground leads and package bottom should be connected directly to the ground plane similar to that shown above. The evaluation circuit board shown above is available from Hittite Microwave Corporation upon request.